

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/09/2022

Details for "TLV73325PQDBVRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLV73325PQDBVRQ1	NIPDAU	Level-2-260C-1 YEAR	TI PHILIPPINES A/T	DBV   5	2.9x1.6x1.45	32.2

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Precious Metals	Gold	7440-57-5	0.036983	100	1000000	0.114687	1147
Sub-Total			<b>0.036983</b>	<b>100</b>	<b>1000000</b>	<b>0.114687</b>	<b>1147</b>
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.058003	75.000323	750003	0.179871	1799
Thermoplastics	Epoxy	85954-11-6	0.019334	24.999677	249997	0.059956	600
Sub-Total			<b>0.077337</b>	<b>100</b>	<b>1000000</b>	<b>0.239828</b>	<b>2398</b>
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	19.439115	97.05	970500	60.28209	602821
Copper and Its Alloys	Iron	7439-89-6	0.52078	2.6	26000	1.614976	16150
Copper and Its Alloys	Phosphorus	7723-14-0	0.030045	0.15	1500	0.093172	932
Zinc and Its Alloys	Zinc	7440-66-6	0.04006	0.2	2000	0.124229	1242
Sub-Total			<b>20.03</b>	<b>100</b>	<b>1000000</b>	<b>62.114467</b>	<b>621145</b>
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.066584	95.12	951200	0.206482	2065
Precious Metals	Gold	7440-57-5	0.000546	0.78	7800	0.001693	17
Precious Metals	Palladium	7440-05-3	0.00287	4.1	41000	0.0089	89
Sub-Total			<b>0.07</b>	<b>100</b>	<b>1000000</b>	<b>0.217075</b>	<b>2171</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	10.427803	88.000008	880000	32.337365	323374
Other Organic Materials	Chlorine	7782-50-5	0.000118	0.000996	10	0.000366	4
Other Plastics and Rubber	Carbon Black	1333-86-4	0.035549	0.299997	3000	0.11024	1102
Thermoplastics	Epoxy	85954-11-6	1.386305	11.698999	116990	4.299031	42990
Sub-Total			<b>11.849775</b>	<b>100</b>	<b>1000000</b>	<b>36.747002</b>	<b>367470</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.182821	100	1000000	0.566941	5669
Sub-Total			<b>0.182821</b>	<b>100</b>	<b>1000000</b>	<b>0.566941</b>	<b>5669</b>
<b>Total</b>			<b>32.246916</b>			<b>100</b>	<b>1000000</b>

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/eecoinfo](http://www.ti.com/eecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.